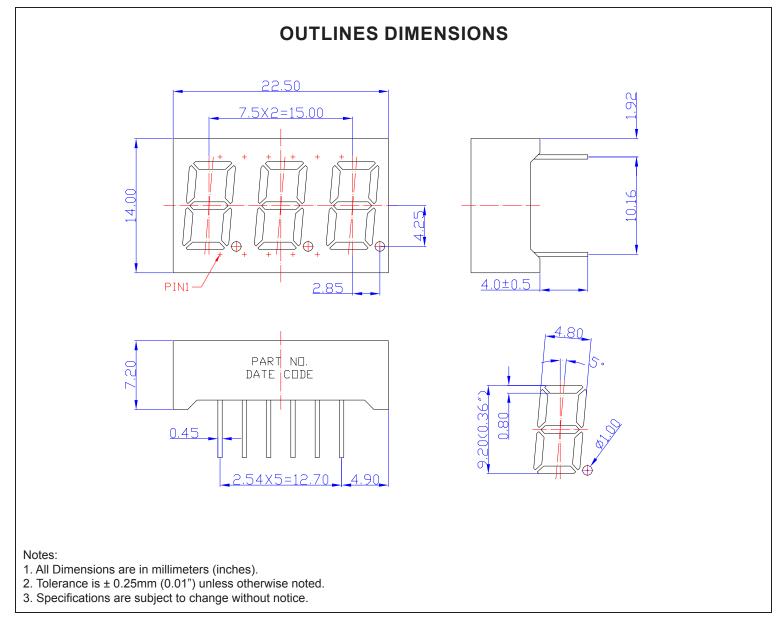


#### SPECIFICATIONS



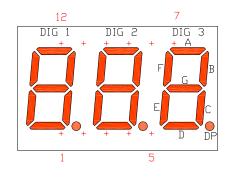


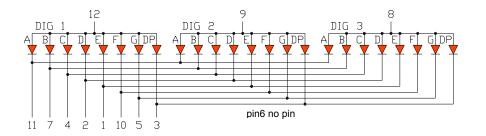
Part Number	Chip Material	Color of Emission	Lens Type	Description	
CDTA36R2WF	InGaAIP	Red	White Segment	Common Anode	





## TYPICAL INTERNAL EQUIVALENT CIRCUIT









#### ABSOLUTE MAXIMUM RATINGS

#### (TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	70	mW			
Pulse Forward Current	lfp	90	mA			
Continuous Forward Current	lF	25	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width $\leq$ 10 ms, Duty Ratio $\leq$ 1/10. Soldering Condition: 260 °C/ 5sec						

# OPTICAL-ELECTRICAL CHARACTERISTICS

# (TA=25°C)

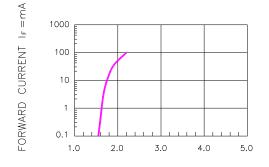
Deremeter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 20mA	-	20	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	2.0	2.6	V
Reverse Leakage Current	lr	V <sub>R</sub> = 5V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	650	-	nm
Dominant Wavelength	λD	l⊧ = 20mA	-	639	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm



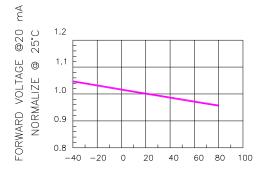


## **OPTICAL CHARACTERISTIC CURVES**

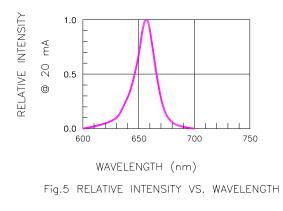


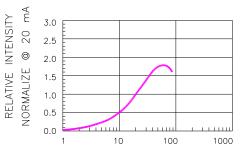


FORWARD VOLTAGE (V) Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE

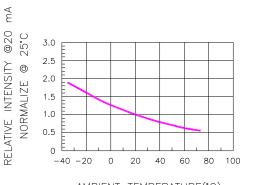


AMBIENT TEMPERATURE(\*C) Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

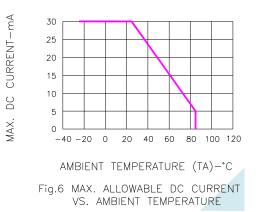




FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT



AMBIENT TEMPERATURE(°C) Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

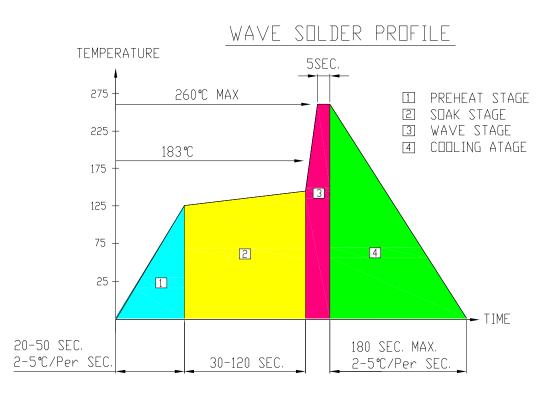






### SOLDERING CONDITIONS – DISPLAY TYPE LED

# • RECOMMEND SOLDERING PROFILE



#### Note:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- No more than one wave soldering pass

# • SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should

be shorter (+10°C $\rightarrow$ 1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

#### REWORK

Customer must finish rework within  $\leq 3 \text{ sec under } 350^{\circ}\text{C}$ . The head of soldering iron cannot touch copper foil.

